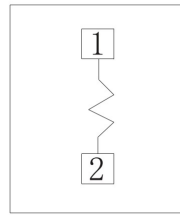


Features

- Withstand high current
- Small size
- Can customize according to requirements

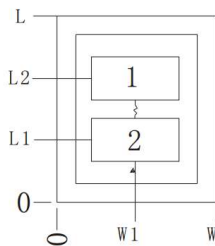
Function Diagram



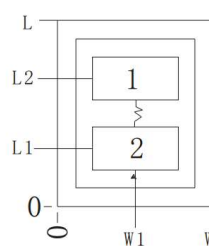
Electrical Specifications (Ta=+25°C, 50Ω system)

Part Number	W	W1	L	L1	L2	Standard Resistance (Ω)	Handling Power(W)
	um	um	um	um	um		
BW1687	550	270	650	218	432	5	0.45
BW1688	550	275	650	203	447	10	0.9

Outline Size



BW1687



BW1688

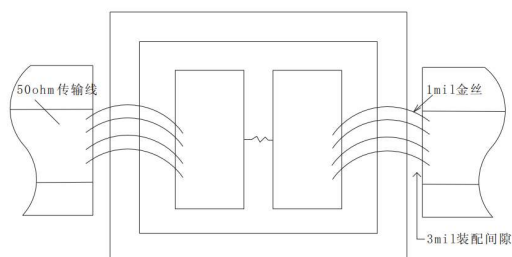
Note:

1. Unit: um
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated, Pad size: BW1687, 300*150(um)
BW1688, 300*150(um)
5. Don't bonding on thru holds
6. Tolerance: ±50um


Pads Definition

Number	Symbol	Description
1、2	In, Out	Input and output ports
	GND	Bottom must be grounded

Application



Bonding Definition

Max. Handling Power	0.45W
Junction Temperature	225°C
Storage Temperature	-65~+150°C
Operating Temperature	-55~+125°C
Static Protection (HBM)	Class 1A
 ELECTROSTATIC SENSITIVE DEVICE OBSERVE HANDLING PRECAUTIONS	